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- UG-855: Evaluation Board for the AD7124-4 4-Channel, Low Noise, Low Power, 24-Bit, Sigma-Delta ADC with In-Amp and Reference

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- AD7124-4/AD7124-8 Eval+ Software

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- CN0376
- CN0381
- CN0382
- CN0383
- CN0384

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5/2015—Revision 0: Initial Version

GENERAL DESCRIPTION

The AD7124-4 is a low power, low noise, completely integrated analog front end for high precision measurement applications. The device contains a low noise, 24-bit Σ - Δ analog-to-digital converter (ADC), and can be configured to have four differential inputs or seven single-ended or pseudo differential inputs. The on-chip low gain stage ensures that signals of small amplitude can be interfaced directly to the ADC.

One of the major advantages of the AD7124-4 is that it gives the user the flexibility to employ one of three integrated power modes. The current consumption, range of output data rates, and rms noise can be tailored with the power mode selected. The device also offers a multitude of filter options, ensuring that the user has the highest degree of flexibility.

The AD7124-4 can achieve simultaneous 50 Hz and 60 Hz rejection when operating at an output data rate of 25 SPS (single cycle settling), with rejection in excess of 80 dB achieved at lower output data rates.

The AD7124-4 establishes the highest degree of signal chain integration. The device contains a precision, low noise, low drift internal band gap reference, and also accepts an external differential reference, which can be internally buffered. Other key integrated features include programmable low drift excitation current sources, burnout currents, and a bias voltage generator, which sets the common-mode voltage of a channel to $AV_{DD}/2$. The low-side power switch enables the user to power down bridge sensors between conversions, ensuring the absolute minimal power consumption of the system. The device also allows the user the option of operating with either an internal clock or an external clock.

The integrated channel sequencer allows several channels to be enabled simultaneously, and the AD7124-4 sequentially converts on each enabled channel, simplifying communication with the device. As many as 16 channels can be enabled at any time; a channel being defined as an analog input or a diagnostic such as a power supply check or a reference check. This unique feature allows diagnostics to be interleaved with conversions. The AD7124-4 also supports per channel configuration. The device allows eight configurations or setups. Each configuration consists of gain, filter type, output data rate, buffering, and reference source. The user can assign any of these setups on a channel by channel basis.

The AD7124-4 also has extensive diagnostic functionality integrated as part of its comprehensive feature set. These diagnostics include a cyclic redundancy check (CRC), signal chain checks, and serial interface checks, which lead to a more robust solution. These diagnostics reduce the need for external components to implement diagnostics, resulting in reduced board space needs, reduced design cycle times, and cost savings. The failure modes effects and diagnostic analysis (FMEDA) of a typical application has shown a safe failure fraction (SFF) greater than 90% according to IEC 61508.

The device operates with a single analog power supply from 2.7 V to 3.6 V or a dual 1.8 V power supply. The digital supply has a range of 1.65 V to 3.6 V. It is specified for a temperature range of -40°C to $+125^{\circ}\text{C}$. The AD7124-4 is housed in a 32-lead LFCSP package and a 24-lead TSSOP package.

Note that, throughout this data sheet, multifunction pins, such as $\overline{\text{DOUT}}/\overline{\text{RDY}}$, are referred to either by the entire pin name or by a single function of the pin, for example, $\overline{\text{RDY}}$, when only that function is relevant.

Table 1. AD7124-4 Overview

Parameter	Low Power Mode	Mid Power Mode	Full Power Mode
Maximum Output Data Rate	2400 SPS	4800 SPS	19,200 SPS
RMS Noise (Gain = 128)	24 nV	20 nV	23 nV
Peak-to-Peak Resolution at 1200 SPS (Gain = 1)	16.4 bits	17.1 bits	18 bits
Typical Current (ADC + PGA)	255 μA	355 μA	930 μA

SPECIFICATIONS

$AV_{DD} = 2.9\text{ V to }3.6\text{ V}$ (full power mode), $2.7\text{ V to }3.6\text{ V}$ (mid and low power mode), $IOV_{DD} = 1.65\text{ V to }3.6\text{ V}$, $AV_{SS} = \text{DGND} = 0\text{ V}$, $\text{REFINx}(+) = 2.5\text{ V}$, $\text{REFINx}(-) = AV_{SS}$, master clock = 614.4 kHz, all specifications T_{MIN} to T_{MAX} , unless otherwise noted.

Table 2.

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
ADC					
Output Data Rate, f_{ADC}					
Low Power Mode	1.17		2400	SPS	
Mid Power Mode	2.34		4800	SPS	
Full Power Mode	9.38		19,200	SPS	
No Missing Codes ²	24			Bits	$FS^3 > 2$, sinc ⁴ filter
	24			Bits	$FS^3 > 8$, sinc ³ filter
Resolution					See the RMS Noise and Resolution section
RMS Noise and Update Rates					See the RMS Noise and Resolution section
Integral Nonlinearity (INL)	-4	±1	+4	ppm of FSR	Gain = 1 ²
	-15	±2	+15	ppm of FSR	Gain > 1 ⁴
Offset Error ⁵					
Before Calibration		±15		μV	Gain = 1 to 8
After Internal Calibration/System Calibration		200/gain		μV	Gain = 16 to 128
In order of noise					
Offset Error Drift vs. Temperature ⁶					
Low Power Mode		10		nV/°C	Gain = 1 or gain > 16
		80		nV/°C	Gain = 2 to 8
		40		nV/°C	Gain = 16
Mid Power Mode		10		nV/°C	Gain = 1 or gain > 16
		40		nV/°C	Gain = 2 to 8
		20		nV/°C	Gain = 16
Full Power Mode		10		nV/°C	
Gain Error ^{5,7}					
Before Internal Calibration	-0.0025		+0.0025	%	Gain = 1, $T_A = 25^\circ\text{C}$
		-0.3		%	Gain > 1
After Internal Calibration	-0.016	+0.004	+0.016	%	Gain = 2 to 8, $T_A = 25^\circ\text{C}$
		±0.025		%	Gain = 16 to 128
After System Calibration		In order of noise			
Gain Error Drift vs. Temperature		1	2	ppm/°C	
Power Supply Rejection					$A_{IN} = 1\text{ V/gain}$, external reference
Low Power Mode	87			dB	Gain = 2 to 16
	96			dB	Gain = 1 or gain > 16
Mid Power Mode ²	92			dB	Gain = 2 to 16
	100			dB	Gain = 1 or gain > 16
Full Power Mode	99			dB	
Common-Mode Rejection ⁸					
At DC ²	85	90		dB	$A_{IN} = 1\text{ V}$, gain = 1
	105	115		dB	$A_{IN} = 1\text{ V/gain}$, gain 2 or 4
	102 ^{9,2}			dB	$A_{IN} = 1\text{ V/gain}$, gain 2 or 4
	115	120		dB	$A_{IN} = 1\text{ V/gain}$, gain ≥ 8
	105 ^{9,2}			dB	$A_{IN} = 1\text{ V/gain}$, gain ≥ 8
Sinc ³ , Sinc ⁴ Filter ²					
At 50 Hz, 60 Hz	120			dB	10 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
At 50 Hz	120			dB	50 SPS, 50 Hz ± 1 Hz
At 60 Hz	120			dB	60 SPS, 60 Hz ± 1 Hz

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
Fast Settling Filters ²					
At 50 Hz	115			dB	First notch at 50 Hz, 50 Hz ± 1 Hz
At 60 Hz	115			dB	First notch at 60 Hz, 60 Hz ± 1 Hz
Post Filters ²					
At 50 Hz, 60 Hz	130			dB	20 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	130			dB	25 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
Normal Mode Rejection ²					
Sinc ⁴ Filter					
External Clock					
At 50 Hz, 60 Hz	120			dB	10 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	80			dB	50 SPS, REJ60 ¹⁰ =1, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
At 50 Hz	120			dB	50 SPS, 50 Hz ± 1 Hz
At 60 Hz	120			dB	60 SPS, 60 Hz ± 1 Hz
Internal Clock					
At 50 Hz, 60 Hz	98			dB	10 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	66			dB	50 SPS, REJ60 ¹⁰ = 1, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
At 50 Hz	92			dB	50 SPS, 50 Hz ± 1 Hz
At 60 Hz	92			dB	60 SPS, 60 Hz ± 1 Hz
Sinc ³ Filter					
External Clock					
At 50 Hz, 60 Hz	100			dB	10 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	65			dB	50 SPS, REJ60 ¹⁰ = 1, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
At 50 Hz	100			dB	50 SPS, 50 Hz ± 1 Hz
At 60 Hz	100			dB	60 SPS, 60 Hz ± 1 Hz
Internal Clock					
At 50 Hz, 60 Hz	73			dB	10 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	52			dB	50 SPS, REJ60 ¹⁰ = 1, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
At 50 Hz	68			dB	50 SPS, 50 Hz ± 1 Hz
At 60 Hz	68			dB	60 SPS, 60 Hz ± 1 Hz
Fast Settling Filters					
External Clock					
At 50 Hz	40			dB	First notch at 50 Hz, 50 Hz ± 0.5 Hz
At 60 Hz	40			dB	First notch at 60 Hz, 60 Hz ± 0.5 Hz
Internal Clock					
At 50 Hz	24.5			dB	First notch at 50 Hz, 50 Hz ± 0.5 Hz
At 60 Hz	24.5			dB	First notch at 60 Hz, 60 Hz ± 0.5 Hz
Post Filters					
External Clock					
At 50 Hz, 60 Hz	86			dB	20 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	62			dB	25 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
Internal Clock					
At 50 Hz, 60 Hz	67			dB	20 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
	50			dB	25 SPS, 50 Hz ± 1 Hz, 60 Hz ± 1 Hz
ANALOG INPUTS ¹¹					
Differential Input Voltage Ranges ¹²		±V _{REF} /gain		V	V _{REF} = REFINx(+) – REFINx(-), or internal reference
Absolute A _{IN} Voltage Limits ²					
Gain = 1 (Unbuffered)	AV _{SS} – 0.05		AV _{DD} + 0.05	V	
Gain = 1 (Buffered)	AV _{SS} + 0.1		AV _{DD} – 0.1	V	
Gain > 1	AV _{SS} – 0.05		AV _{DD} + 0.05	V	

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
Analog Input Current Gain > 1 or Gain = 1 (Buffered)					
Low Power Mode					
Absolute Input Current		±1		nA	
Differential Input Current		±0.2		nA	
Analog Input Current Drift		25		pA/°C	
Mid Power Mode					
Absolute Input Current		±1.2		nA	
Differential Input Current		±0.4		nA	
Analog Input Current Drift		25		pA/°C	
Full Power Mode					
Absolute Input Current		±3.3		nA	
Differential Input Current		±1.5		nA	
Analog Input Current Drift		25		pA/°C	
Gain = 1 (Unbuffered)					Current varies with input voltage
Absolute Input Current		±2.65		μA/V	
Analog Input Current Drift		1.1		nA/V/°C	
REFERENCE INPUT					
Internal Reference					
Initial Accuracy	2.5 – 0.2%	2.5	2.5 + 0.2%	V	T _A = 25°C
Drift		2	10	ppm/°C	TSSOP
		2	15	ppm/°C	LFCSP
Output Current			10	mA	
Load Regulation		50		μV/mA	
Power Supply Rejection		85		dB	
External Reference					
External REF _{IN} Voltage ²	1	2.5	AV _{DD}	V	REF _{IN} = REF _{INx} (+) – REF _{INx} (-)
Absolute REF _{IN} Voltage Limits ²	AV _{SS} – 0.05		AV _{DD} + 0.05	V	Unbuffered
	AV _{SS} + 0.1		AV _{DD} – 0.1	V	Buffered
Reference Input Current					
Buffered					
Low Power Mode					
Absolute Input Current		±0.5		nA	
Reference Input Current Drift		10		pA/°C	
Mid Power Mode					
Absolute Input Current		±1		nA	
Reference Input Current Drift		10		pA/°C	
Full Power Mode					
Absolute Input Current		±3		nA	
Reference Input Current Drift		10		pA/°C	
Unbuffered					
Absolute Input Current		±12		μA	
Reference Input Current Drift		6		nA/°C	
Normal Mode Rejection					Same as for analog inputs
Common-Mode Rejection		100		dB	

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
EXCITATION CURRENT SOURCES (IOUT0/IOUT1)					
Output Current		50/100/250/ 500/750/1000		μA	Available on any analog input pin
Initial Tolerance		±4		%	T _A = 25°C
Drift		50		ppm/°C	
Current Matching		±0.5		%	Matching between IOUT0 and IOUT1, V _{OUT} = 0 V
Drift Matching ²		5	30	ppm/°C	
Line Regulation (AV _{DD})		2		%/V	AV _{DD} = 3 V ± 5%
Load Regulation		0.2		%/V	
Output Compliance ²	AV _{SS} – 0.05		AV _{DD} – 0.37	V	50 μA/100 μA/250 μA/500 μA current sources, 2% accuracy
	AV _{SS} – 0.05		AV _{DD} – 0.48	V	750 μA and 1000 μA current sources, 2% accuracy
BIAS VOLTAGE (V_{BIAS}) GENERATOR					
V _{BIAS}		AV _{SS} + (AV _{DD} – AV _{SS})/2		V	Available on any analog input pin
V _{BIAS} Generator Start-Up Time		6.7		μs/nF	Dependent on the capacitance connected to AINx
TEMPERATURE SENSOR					
Accuracy		±0.5		°C	
Sensitivity		13,584		Codes/°C	
LOW-SIDE POWER SWITCH					
On Resistance (R _{ON})		7	10	Ω	
Allowable Current ²			30	mA	Continuous current
BURNOUT CURRENTS					
A _{IN} Current		0.5/2/4		μA	Analog inputs must be buffered
DIGITAL OUTPUTS (P1 AND P2)					
Output Voltage					
High, V _{OH}	AV _{DD} – 0.6			V	I _{SOURCE} = 100 μA
Low, V _{OL}			0.4	V	I _{SINK} = 100 μA
DIAGNOSTICS					
Power Supply Monitor Detect Level					
Analog Low Dropout Regulator (ALDO)			1.6	V	AV _{DD} – AV _{SS} ≥ 2.7 V
Digital LDO (DLDO)			1.55	V	IOV _{DD} ≥ 1.75 V
Reference Detect Level	0.7		1	V	REF_DET_ERR bit active if V _{REF} < 0.7 V
AINM/AINP Overvoltage Detect Level	AV _{DD} + 0.04			V	
AINM/AINP Undervoltage Detect Level			AV _{SS} – 0.04	V	
INTERNAL/EXTERNAL CLOCK					
Internal Clock					
Frequency	614.4 – 5%	614.4	614.4 + 5%	kHz	
Duty Cycle		50:50		%	
External Clock					
Frequency		2.4576		MHz	Internal divide by 4
Duty Cycle Range		45:55 to 55:45		%	
LOGIC INPUTS²					
Input Voltage					
Low, V _{INL}			0.3 × IOV _{DD}	V	1.65 V ≤ IOV _{DD} < 1.9 V
			0.35 × IOV _{DD}	V	1.9 V ≤ IOV _{DD} < 2.3 V
			0.7	V	2.3 V ≤ IOV _{DD} ≤ 3.6 V
High, V _{INH}	0.7 × IOV _{DD}			V	1.65 V ≤ IOV _{DD} < 1.9 V
	0.65 × IOV _{DD}			V	1.9 V ≤ IOV _{DD} < 2.3 V
	1.7			V	2.3 V ≤ IOV _{DD} < 2.7 V
	2			V	2.7 V ≤ IOV _{DD} ≤ 3.6 V
Hysteresis	0.2		0.6	V	1.65 V ≤ IOV _{DD} ≤ 3.6 V
Input Currents	–1		+1	μA	V _{IN} = IOV _{DD} or GND
Input Capacitance		10		pF	All digital inputs

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
LOGIC OUTPUTS (INCLUDING CLK)					
Output Voltage ²					
High, V_{OH}	$IOV_{DD} - 0.35$			V	$I_{SOURCE} = 100 \mu A$ $I_{SINK} = 100 \mu A$
Low, V_{OL}			0.4	V	
Floating State Leakage Current	-1		+1	μA	
Floating State Output Capacitance		10		pF	
Data Output Coding		Offset binary			
SYSTEM CALIBRATION²					
Calibration Limit					
Full Scale (FS)			$1.05 \times FS$	V	
Zero Scale	$-1.05 \times FS$			V	
Input Span	$0.8 \times FS$		$2.1 \times FS$	V	
POWER SUPPLY VOLTAGES FOR ALL POWER MODES					
AV_{DD} to AV_{SS}					
Low Power Mode	2.7		3.6	V	
Mid Power Mode	2.7		3.6	V	
Full Power Mode	2.9		3.6	V	
IOV_{DD} to GND	1.65		3.6	V	
AV_{SS} to GND	-1.8		0	V	
IOV_{DD} to AV_{SS}			5.4	V	
POWER SUPPLY CURRENTS^{11,13}					
I_{AVDD} , External Reference					
Low Power Mode					
Gain = 1 ²		125	140	μA	All buffers off
Gain = 1 I_{AVDD} Increase per AINx Buffer ²		15	25	μA	
Gain = 2 to 8		205	250	μA	
Gain = 16 to 128		235	300	μA	
I_{AVDD} Increase per Reference Buffer ²		10	20	μA	All gains
Mid Power Mode					
Gain = 1 ²		150	170	μA	All buffers off
Gain = 1 I_{AVDD} Increase per AINx Buffer ²		30	40	μA	
Gain = 2 to 8		275	345	μA	
Gain = 16 to 128		330	430	μA	
I_{AVDD} Increase per Reference Buffer ²		20	30	μA	All gains
Full Power Mode					
Gain = 1 ²		315	350	μA	All buffers off
Gain = 1 I_{AVDD} Increase per AINx Buffer ²		90	135	μA	
Gain = 2 to 8		660	830	μA	
Gain = 16 to 128		875	1200	μA	
I_{AVDD} Increase per Reference Buffer ²		85	120	μA	All gains
I_{AVDD} Increase					
Due to Internal Reference ²		50	70	μA	Independent of power mode; the reference buffers are not required when using this reference
Due to V_{BIAS} ²		15	20	μA	
Due to Diagnostics ²		4	5	μA	
I_{IOVDD}					
Low Power Mode		20	35	μA	
Mid Power Mode		25	40	μA	
Full Power Mode		55	80	μA	

Parameter ¹	Min	Typ	Max	Unit	Test Conditions/Comments
POWER-DOWN CURRENTS ¹³					Independent of power mode
Standby Current					LDOs on only
I_{AVDD}		7	15	μA	
I_{IOVDD}		8	20	μA	
Power-Down Current					
I_{AVDD}		1	3	μA	
I_{IOVDD}		1	2	μA	

¹ Temperature range = -40°C to $+125^{\circ}\text{C}$.

² These specifications are not production tested but are supported by characterization data at the initial product release.

³ FS is the decimal equivalent of the FS[10:0] bits in the filter registers.

⁴ The integral nonlinearity is production tested in full power mode only. For other power modes, the specification is supported by characterization data at the initial product release.

⁵ Following a system or internal zero-scale calibration, the offset error is in the order of the noise for the programmed gain and output data rate selected. A system full-scale calibration reduces the gain error to the order of the noise for the programmed gain and output data rate.

⁶ Recalibration at any temperature removes these errors.

⁷ Gain error applies to both positive and negative full-scale. A factory calibration is performed at gain = 1, $T_A = 25^{\circ}\text{C}$.

⁸ When gain > 1, the common-mode voltage is between $(AV_{SS} + 0.1 + 0.5/\text{gain})$ and $(AV_{DD} - 0.1 - 0.5/\text{gain})$.

⁹ Specification is for a wider common-mode voltage between $(AV_{SS} - 0.05 + 0.5/\text{gain})$ and $(AV_{DD} - 0.1 - 0.5/\text{gain})$.

¹⁰ REJ60 is a bit in the filter registers. When the first notch of the sinc filter is at 50 Hz, a notch is placed at 60 Hz when REJ60 is set to 1. This gives simultaneous 50 Hz and 60 Hz rejection.

¹¹ When the gain is greater than 1, the analog input buffers are enabled automatically. The buffers can only be disabled when the gain equals 1.

¹² When $V_{REF} = (AV_{DD} - AV_{SS})$, the typical differential input equals $0.92 \times V_{REF}/\text{gain}$ for the low and mid power modes and $0.86 \times V_{REF}/\text{gain}$ for full power mode.

¹³ The digital inputs are equal to IOV_{DD} or DGND with excitation currents and bias voltage generator disabled.

TIMING CHARACTERISTICS

$AV_{DD} = 2.9\text{ V}$ to 3.6 V (full power mode), 2.7 V to 3.6 V (mid and low power mode), $IOV_{DD} = 1.65\text{ V}$ to 3.6 V , $AV_{SS} = \text{DGND} = 0\text{ V}$, Input Logic 0 = 0 V, Input Logic 1 = IOV_{DD}, unless otherwise noted.

Table 3.

Parameter ^{1,2}	Min	Typ	Max	Unit	Test Conditions/Comments
t_3	100			ns	SCLK high pulse width
t_4	100			ns	SCLK low pulse width
t_{12}					Delay between consecutive read/write operations
	3/MCLK ³			ns	Full power mode
	12/MCLK			ns	Mid power mode
	24/MCLK			ns	Low power mode
t_{13}				μs	DOUT/ $\overline{\text{RDY}}$ high time if DOUT/ $\overline{\text{RDY}}$ is low and the next conversion is available
		6		μs	Full power mode
		25		μs	Mid power mode
		50		μs	Low power mode
t_{14}					$\overline{\text{SYNC}}$ low pulse width
	3/MCLK			ns	Full power mode
	12/MCLK			ns	Mid power mode
	24/MCLK			ns	Low power mode
READ OPERATION					
t_1	0		80	ns	$\overline{\text{CS}}$ falling edge to DOUT/ $\overline{\text{RDY}}$ active time
t_2^4	0		80	ns	SCLK active edge ⁵ to data valid delay
$t_5^{6,7}$	10		80	ns	Bus relinquish time after $\overline{\text{CS}}$ inactive edge
t_6	0			ns	SCLK inactive edge to $\overline{\text{CS}}$ inactive edge
t_7^8					SCLK inactive edge to DOUT/ $\overline{\text{RDY}}$ high
	10			ns	The DOUT_RDY_DEL bit is cleared, the $\overline{\text{CS}}_{\text{EN}}$ bit is cleared
	110			ns	The DOUT_RDY_DEL bit is set, the $\overline{\text{CS}}_{\text{EN}}$ bit is cleared
t_{7A}^7	t_5			ns	Data valid after $\overline{\text{CS}}$ inactive edge, the $\overline{\text{CS}}_{\text{EN}}$ bit is set

Parameter ^{1,2}	Min	Typ	Max	Unit	Test Conditions/Comments
WRITE OPERATION					
t_8	0			ns	\overline{CS} falling edge to SCLK active edge ⁵ setup time
t_9	30			ns	Data valid to SCLK edge setup time
t_{10}	25			ns	Data valid to SCLK edge hold time
t_{11}	0			ns	\overline{CS} rising edge to SCLK edge hold time

- ¹ These specifications were sample tested during the initial release to ensure compliance. All input signals are specified with $t_r = t_f = 5$ ns (10% to 90% of IOV_{DD} and timed from a voltage level of $IOV_{DD}/2$.
- ² See Figure 3, Figure 4, Figure 5, and Figure 6.
- ³ MCLK is the master clock frequency.
- ⁴ These specifications are measured with the load circuit shown in Figure 2 and defined as the time required for the output to cross the V_{OL} or V_{OH} limits.
- ⁵ The SCLK active edge is the falling edge of SCLK.
- ⁶ These specifications are derived from the measured time taken by the data output to change by 0.5 V when loaded with the circuit shown in Figure 2. The measured number is then extrapolated back to remove the effects of charging or discharging the 25 pF capacitor. The times quoted in the timing characteristics are the true bus relinquish times of the device and, therefore, are independent of external bus loading capacitances.
- ⁷ \overline{RDY} returns high after a read of the ADC. In single conversion mode and continuous conversion mode, the same data can be read again, if required, while \overline{RDY} is high, although subsequent reads must not occur close to the next output update. In continuous read mode, the digital word can be read only once.
- ⁸ When the $\overline{CS_EN}$ bit is cleared, the DOUT/ \overline{RDY} pin changes from its DOUT function to its \overline{RDY} function, following the last inactive edge of the SCLK. When $\overline{CS_EN}$ is set, the DOUT pin continues to output the LSB of the data until the \overline{CS} inactive edge.

Timing Diagrams

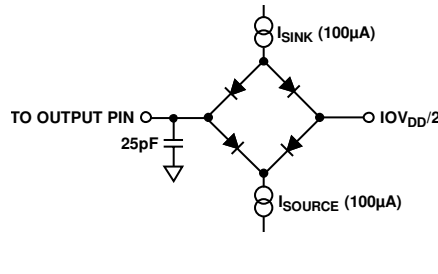


Figure 2. Load Circuit for Timing Characterization

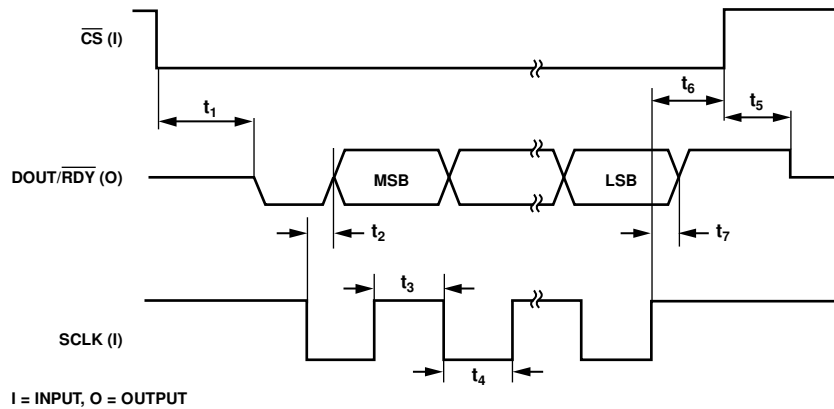


Figure 3. Read Cycle Timing Diagram ($\overline{CS_EN}$ Bit Cleared)

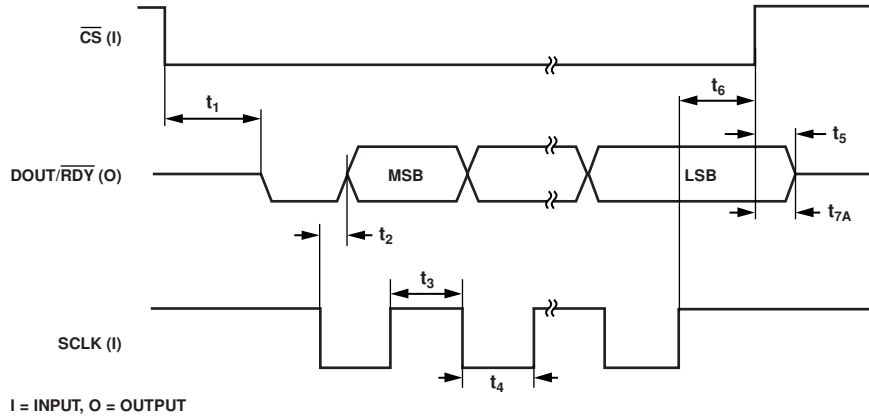


Figure 4. Read Cycle Timing Diagram ($\overline{CS_EN}$ Bit Set)

13197-004

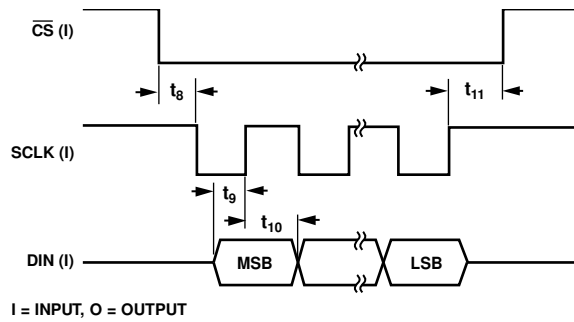


Figure 5. Write Cycle Timing Diagram

13197-005

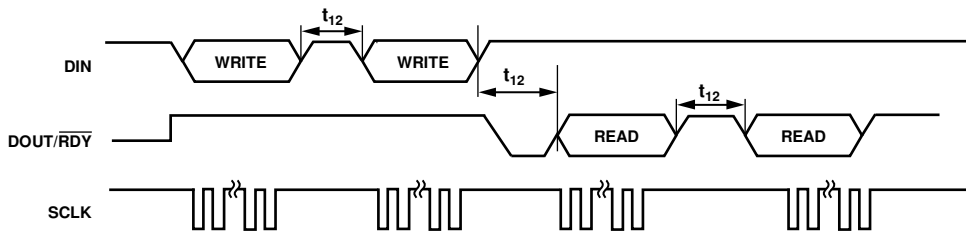


Figure 6. Delay Between Consecutive Serial Operations

13197-006

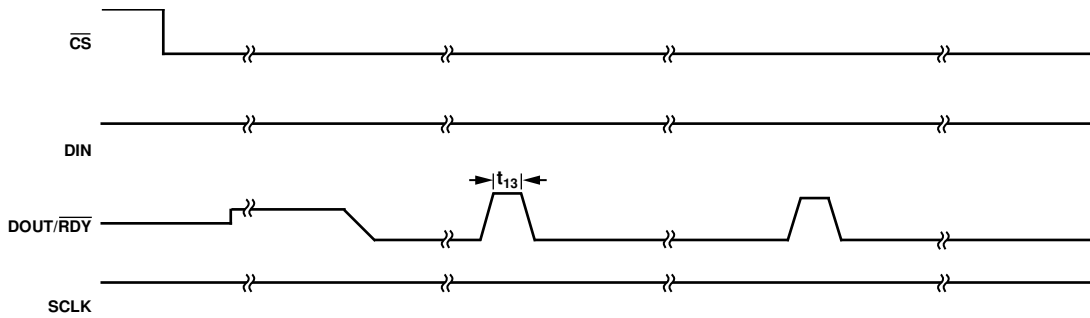


Figure 7. $\overline{DOUT/RDY}$ High Time when $\overline{DOUT/RDY}$ is Initially Low and the Next Conversion is Available

13197-007

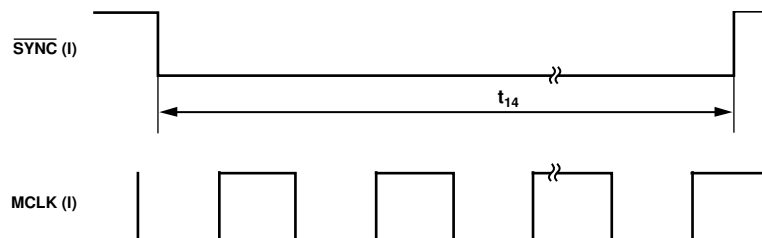


Figure 8. \overline{SYNC} Pulse Width

13197-008

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 4.

Parameter	Rating
AV_{DD} to AV_{SS}	-0.3 V to +3.96 V
IOV_{DD} to DGND	-0.3 V to +3.96 V
IOV_{DD} to AV_{SS}	-0.3 V to +5.94 V
AV_{SS} to DGND	-1.98 V to +0.3 V
Analog Input Voltage to AV_{SS}	-0.3 V to $AV_{DD} + 0.3$ V
Reference Input Voltage to AV_{SS}	-0.3 V to $AV_{DD} + 0.3$ V
Digital Input Voltage to DGND	-0.3 V to $IOV_{DD} + 0.3$ V
Digital Output Voltage to DGND	-0.3 V to $IOV_{DD} + 0.3$ V
AINx/Digital Input Current	10 mA
Operating Temperature Range	-40°C to +125°C
Storage Temperature Range	-65°C to +150°C
Maximum Junction Temperature	150°C
Lead Temperature, Soldering	
Reflow	260°C
ESD Ratings	
Human Body Model (HBM)	4 kV
Field-Induced Charged Device Model (FICDM)	1250 V
Machine Model	400 V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

θ_{JA} is specified for the worst case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 5. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
32-Lead LFCSP	32.5	32.71	°C/W
24-Lead TSSOP	128	42	°C/W

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

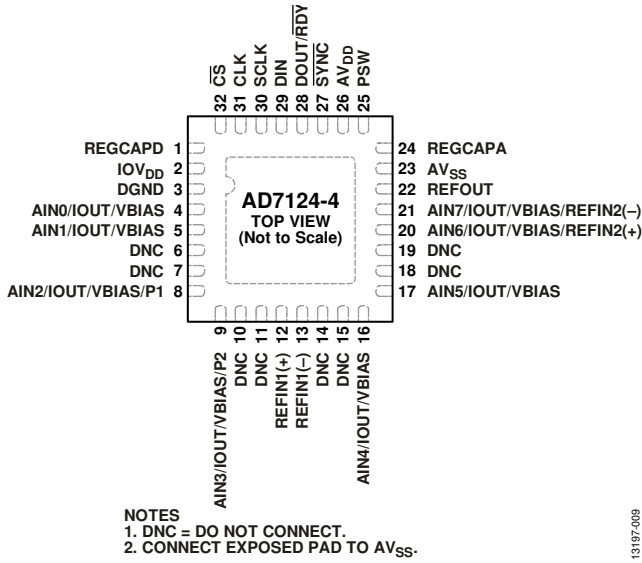


Figure 9. 32-Lead LFCSP Pin Configuration

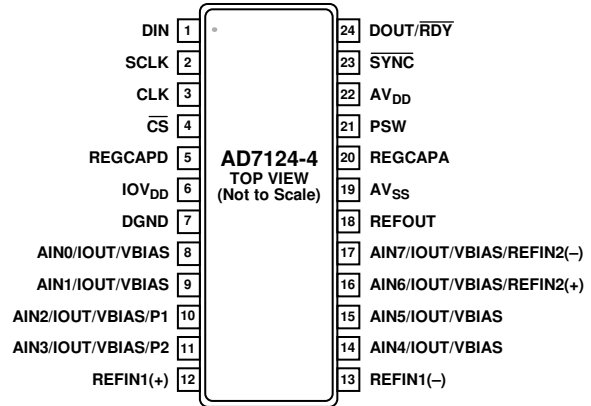


Figure 10. 24-Lead TSSOP Pin Configuration

Table 6. Pin Function Descriptions

Pin No.		Mnemonic	Description
LFCSP	TSSOP		
1	5	REGCAPD	Digital LDO Regulator Output. Decouple this pin to DGND with a 0.1 μ F capacitor.
2	6	IOV _{DD}	Serial Interface Supply Voltage, 1.65 V to 3.6 V. IOV _{DD} is independent of AV _{DD} . Therefore, the serial interface can operate at 1.65 V with AV _{DD} at 3.6 V, for example.
3	7	DGND	Digital Ground Reference Point.
4	8	AIN0/IOUT/VBIAS	Analog Input 0/Output of Internal Excitation Current Source/Bias Voltage. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin.
5	9	AIN1/IOUT/VBIAS	Analog Input 1/Output of Internal Excitation Current Source/Bias Voltage. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin.
6, 7, 10, 11, 14, 15, 18, 19	N/A ¹	DNC	Do Not Connect. Do not connect to these pins.
8	10	AIN2/IOUT/VBIAS/P1	Analog Input 2/Output of Internal Excitation Current Source/Bias Voltage/General-Purpose Output 1. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin. This pin can also be configured as a general-purpose output bit, referenced between AV _{SS} and AV _{DD} .
9	11	AIN3/IOUT/VBIAS/P2	Analog Input 3/Output of Internal Excitation Current Source/Bias Voltage/General-Purpose Output 2. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin. This pin can also be configured as a general-purpose output bit, referenced between AV _{SS} and AV _{DD} .

Pin No.		Mnemonic	Description
LFCSP	TSSOP		
12	12	REFIN1(+)	Positive Reference Input. An external reference can be applied between REFIN1(+) and REFIN1(-). REFIN1(+) can be anywhere between AV_{DD} and $AV_{SS} + 1$ V. The nominal reference voltage (REFIN1(+) – REFIN1(-)) is 2.5 V, but the device functions with a reference from 1 V to AV_{DD} .
13	13	REFIN1(-)	Negative Reference Input. This reference input can be anywhere between AV_{SS} and $AV_{DD} - 1$ V.
16	14	AIN4/IOUT/VBIAS	Analog Input 4/Output of Internal Excitation Current Source/Bias Voltage. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin.
17	15	AIN5/IOUT/VBIAS	Analog Input 5/Output of Internal Excitation Current Source/Bias Voltage. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin.
20	16	AIN6/IOUT/VBIAS/ REFIN2(+)	Analog Input 6/Output of Internal Excitation Current Source/Bias Voltage/Positive Reference Input. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin. This pin also functions as a positive reference input for REFIN2(\pm). REFIN2(+) can be anywhere between AV_{DD} and $AV_{SS} + 1$ V. The nominal reference voltage (REFIN2(+) to REFIN2(-)) is 2.5 V, but the device functions with a reference from 1 V to AV_{DD} .
21	17	AIN7/IOUT/VBIAS/ REFIN2(-)	Analog Input 7/Output of Internal Excitation Current Source/Bias Voltage/Negative Reference Input. This input pin is configured via the configuration registers to be the positive or negative terminal of a differential or pseudo differential input. Alternatively, the internal programmable excitation current source can be made available at this pin. Either IOUT0 or IOUT1 can be switched to this output. A bias voltage midway between the analog power supply rails can be generated at this pin. This pin also functions as the negative reference input for REFIN2(\pm). This reference input can be anywhere between AV_{SS} and $AV_{DD} - 1$ V.
22	18	REFOUT	Internal Reference Output. The buffered output of the internal 2.5 V voltage reference is available on this pin.
23	19	AV_{SS}	Analog Supply Voltage. The voltage on AV_{DD} is referenced to AV_{SS} . The differential between AV_{DD} and AV_{SS} must be between 2.7 V and 3.6 V in mid or low power mode and between 2.9 V and 3.6 V in full power mode. AV_{SS} can be taken below 0 V to provide a dual power supply to the AD7124-4. For example, AV_{SS} can be tied to -1.8 V and AV_{DD} can be tied to +1.8 V, providing a ± 1.8 V supply to the ADC.
24	20	REGCAPA	Analog LDO Regulator Output. Decouple this pin to AV_{SS} with a 0.1 μ F capacitor.
25	21	PSW	Low-Side Power Switch to AV_{SS} .
26	22	AV_{DD}	Analog Supply Voltage, Relative to AV_{SS} .
27	23	$\overline{\text{SYNC}}$	Synchronization Input. This pin is a logic input that allows synchronization of the digital filters and analog modulators when using a number of AD7124-4 devices. When $\overline{\text{SYNC}}$ is low, the nodes of the digital filter, the filter control logic, and the calibration control logic are reset, and the analog modulator is held in a reset state. $\overline{\text{SYNC}}$ does not affect the digital interface but does reset $\overline{\text{RDY}}$ to a high state if it is low.
28	24	$\text{DOUT}/\overline{\text{RDY}}$	Serial Data Output/Data Ready Output. $\text{DOUT}/\overline{\text{RDY}}$ functions as a serial data output pin to access the output shift register of the ADC. The output shift register can contain data from any of the on-chip data or control registers. In addition, $\text{DOUT}/\overline{\text{RDY}}$ operates as a data ready pin, going low to indicate the completion of a conversion. If the data is not read after the conversion, the pin goes high before the next update occurs. The $\text{DOUT}/\overline{\text{RDY}}$ falling edge can also be used as an interrupt to a processor, indicating that valid data is available. With an external serial clock, the data can be read using the $\text{DOUT}/\overline{\text{RDY}}$ pin. When $\overline{\text{CS}}$ is low, the data/control word information is placed on the $\text{DOUT}/\overline{\text{RDY}}$ pin on the SCLK falling edge and is valid on the SCLK rising edge.

Pin No.		Mnemonic	Description
LFCSP	TSSOP		
29	1	DIN	Serial Data Input to the Input Shift Register on the ADC. Data in the input shift register is transferred to the control registers within the ADC, with the register selection bits of the communications register identifying the appropriate register.
30	2	SCLK	Serial Clock Input. This serial clock input is for data transfers to and from the ADC. The SCLK pin has a Schmitt-triggered input, making the interface suitable for opto-isolated applications. The serial clock can be continuous with all data transmitted in a continuous train of pulses. Alternatively, it can be a noncontinuous clock with the information being transmitted to or from the ADC in smaller batches of data.
31	3	CLK	Clock Input/Clock Output. The internal clock can be made available at this pin. Alternatively, the internal clock can be disabled, and the ADC can be driven by an external clock. This allows several ADCs to be driven from a common clock, allowing simultaneous conversions to be performed.
32	4	\overline{CS}	Chip Select Input. This is an active low logic input that selects the ADC. Use \overline{CS} to select the ADC in systems with more than one device on the serial bus or as a frame synchronization signal in communicating with the device. \overline{CS} can be hardwired low if the serial peripheral interface (SPI) diagnostics are unused, allowing the ADC to operate in 3-wire mode with SCLK, DIN, and DOUT interfacing with the device.
		EP	Exposed Pad. Connect the exposed pad to AV_{SS} .

¹ N/A means not applicable.

TYPICAL PERFORMANCE CHARACTERISTICS

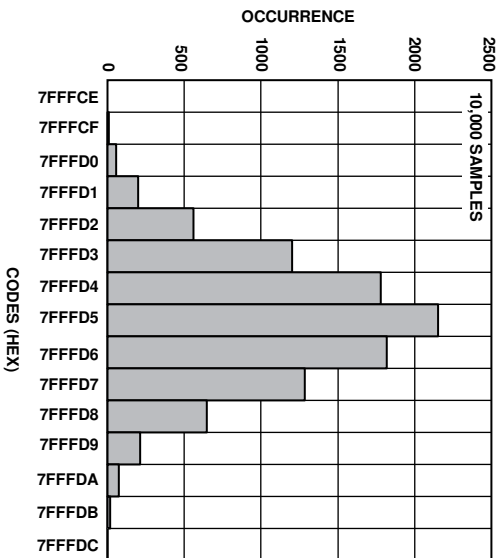


Figure 11. Noise Histogram Plot (Full Power Mode, Post Filter, Output Data)
Rate = 25 SPS, Gain = 1

13197-010

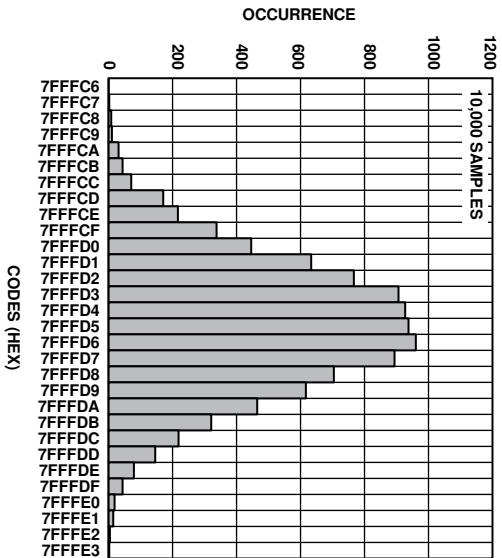


Figure 12. Noise Histogram Plot (Mid Power Mode, Post Filter, Output Data)
Rate = 25 SPS, Gain = 1

13197-012

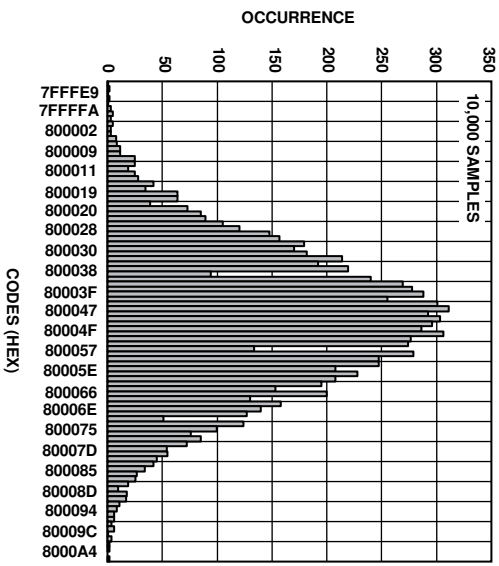


Figure 14. Noise Histogram Plot (Full Power Mode, Post Filter, Output Data)
Rate = 25 SPS, Gain = 128

13197-011

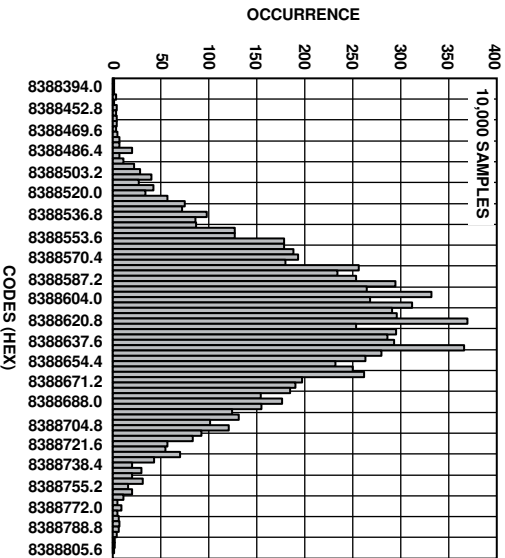


Figure 13. Noise Histogram Plot (Low Power Mode, Post Filter, Output Data)
Rate = 25 SPS, Gain = 1

13197-013

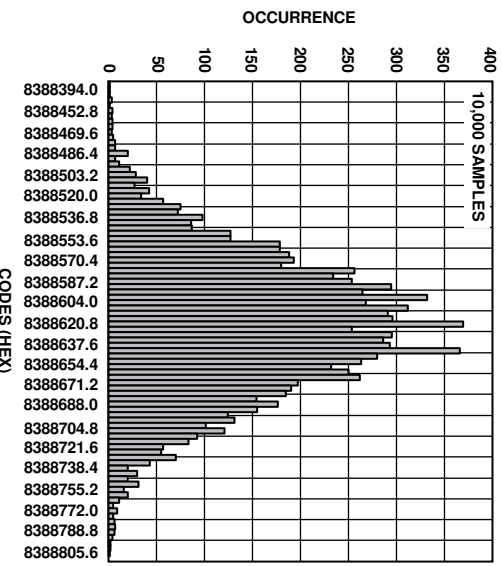


Figure 15. Noise Histogram Plot (Mid Power Mode, Post Filter, Output Data)
Rate = 25 SPS, Gain = 128

13197-013

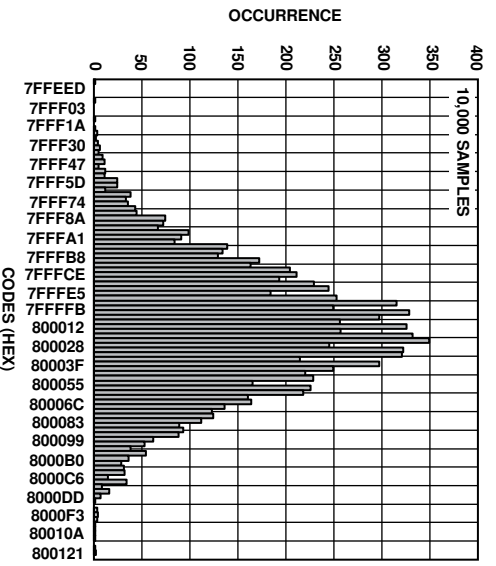


Figure 16. Noise Histogram Plot (Low Power Mode, Post Filter, Output Data)
Rate = 25 SPS, Gain = 128

13197-015

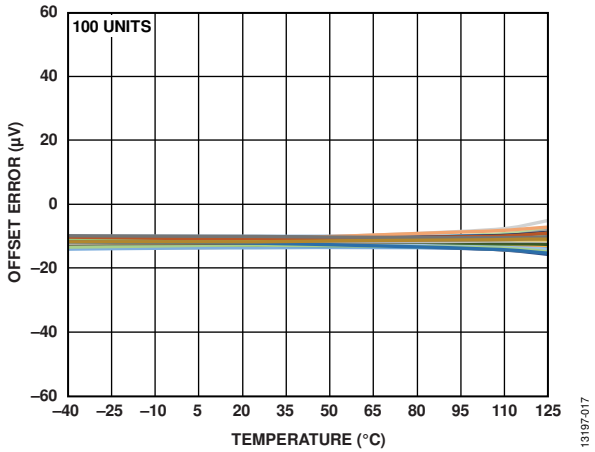


Figure 17. Input Referred Offset Error vs. Temperature (Gain = 8, Full Power Mode)

13197-017

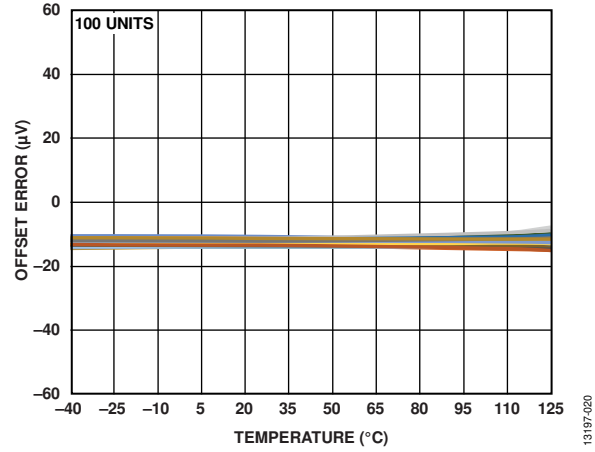


Figure 20. Input Referred Offset Error vs. Temperature (Gain = 16, Full Power Mode)

13197-020

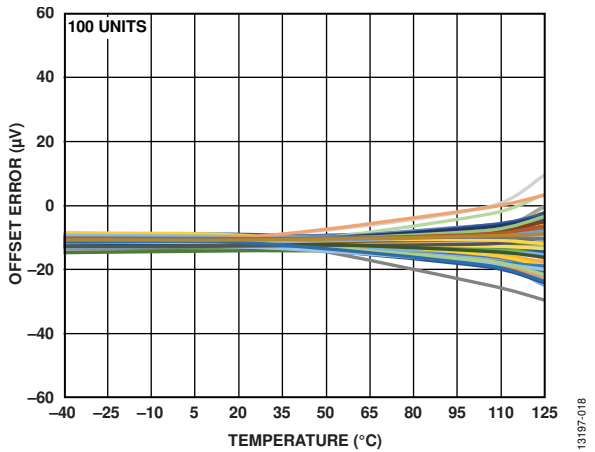


Figure 18. Input Referred Offset Error vs. Temperature (Gain = 8, Mid Power Mode)

13197-018

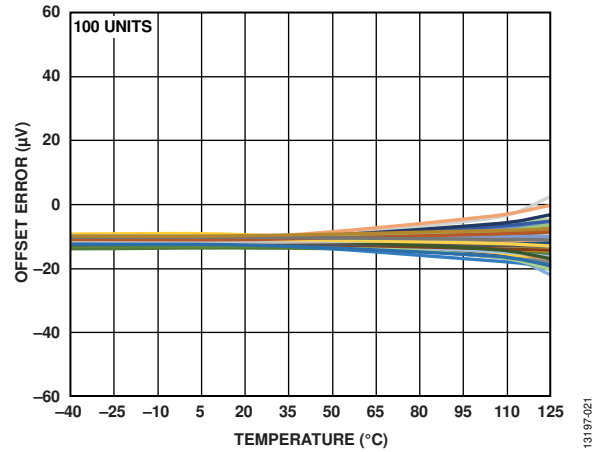


Figure 21. Input Referred Offset Error vs. Temperature (Gain = 16, Mid Power Mode)

13197-021

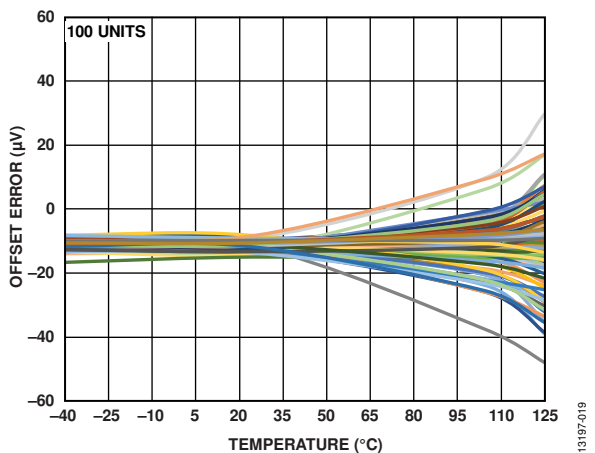


Figure 19. Input Referred Offset Error vs. Temperature (Gain = 8, Low Power Mode)

13197-019

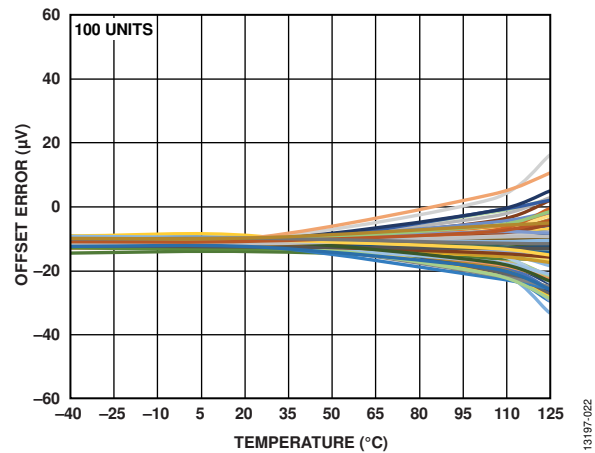


Figure 22. Input Referred Offset Error vs. Temperature (Gain = 16, Low Power Mode)

13197-022

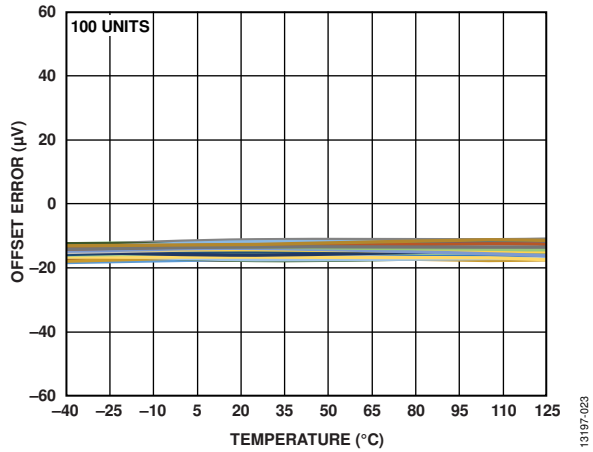


Figure 23. Input Referred Offset Error vs. Temperature (Gain = 1, Analog Input Buffers Enabled)

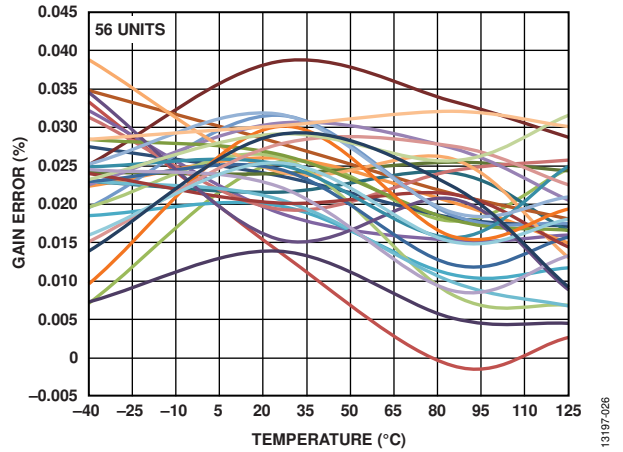


Figure 26. Input Referred Gain Error vs. Temperature (Gain = 16)

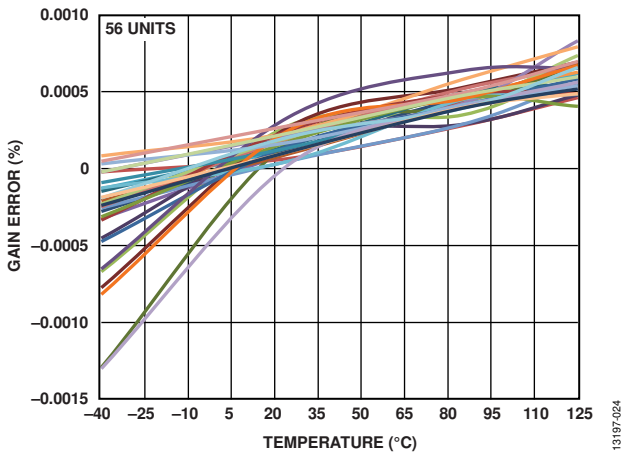


Figure 24. Input Referred Gain Error vs. Temperature (Gain = 1)

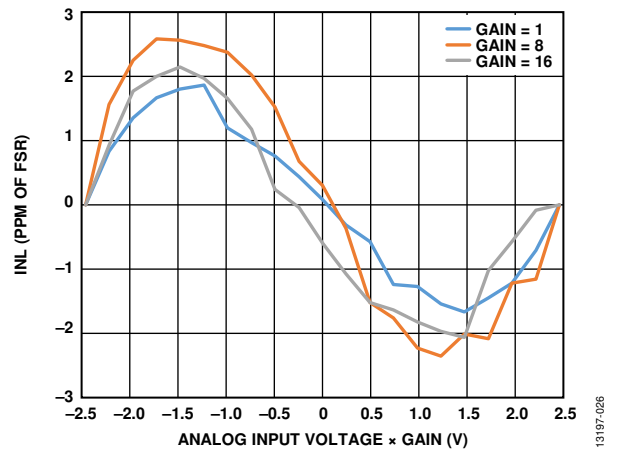


Figure 27. INL vs. Differential Input Signal (Analog Input \times Gain), ODR = 50 SPS, External 2.5 V Reference

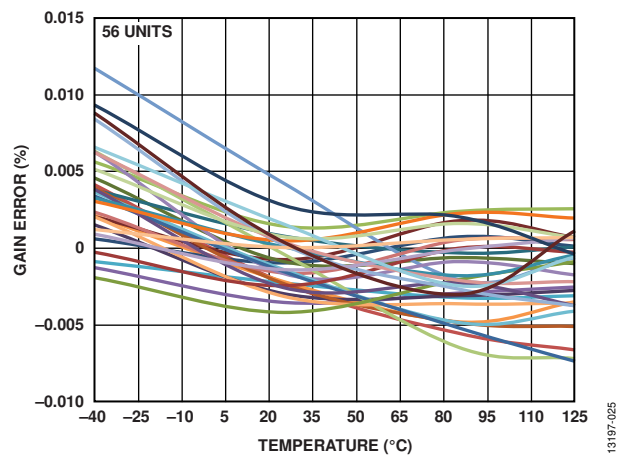


Figure 25. Input Referred Gain Error vs. Temperature (Gain = 8)

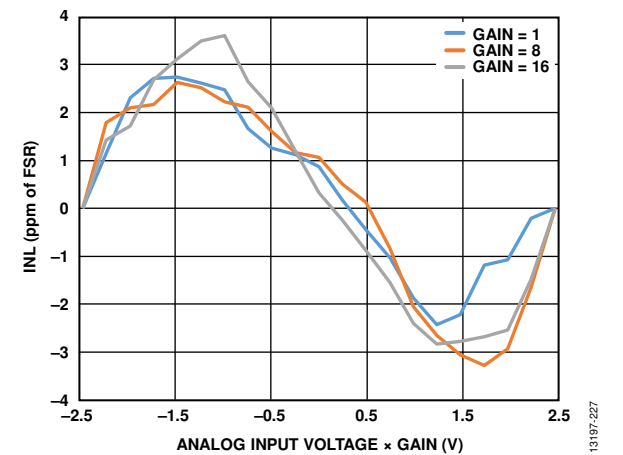


Figure 28. INL vs. Differential Input Signal (Analog Input \times Gain), ODR = 50 SPS, Internal Reference

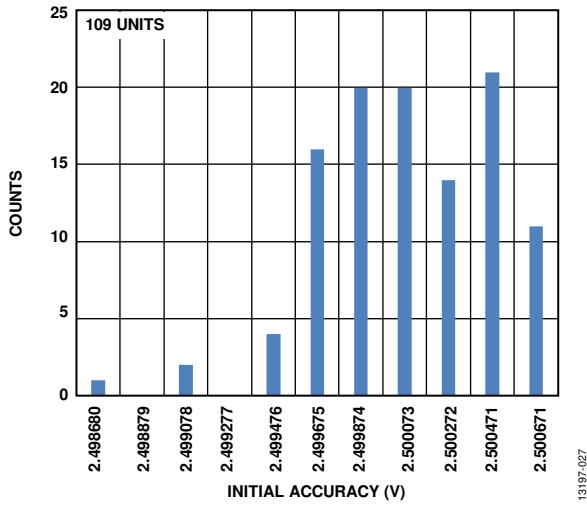


Figure 29. Internal Reference Voltage Histogram

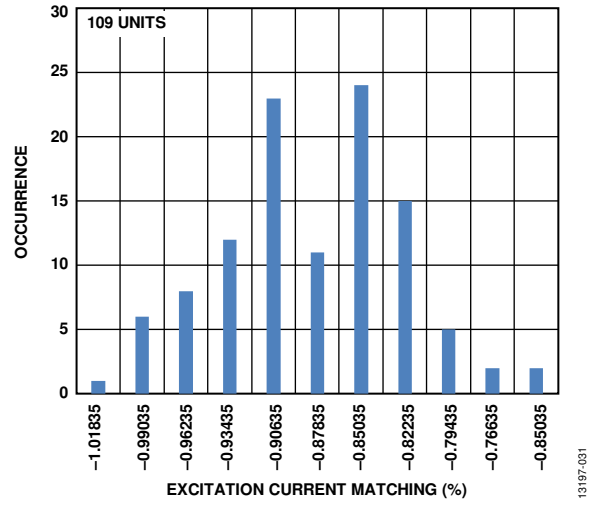


Figure 32. IOUTx Current Initial Matching Histogram (500 µA)

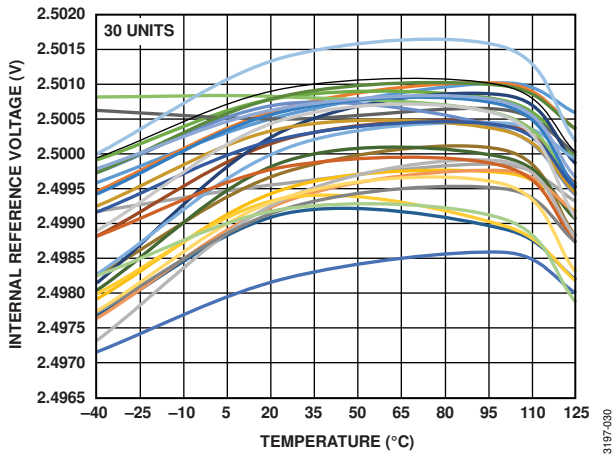


Figure 30. Internal Reference Voltage vs. Temperature

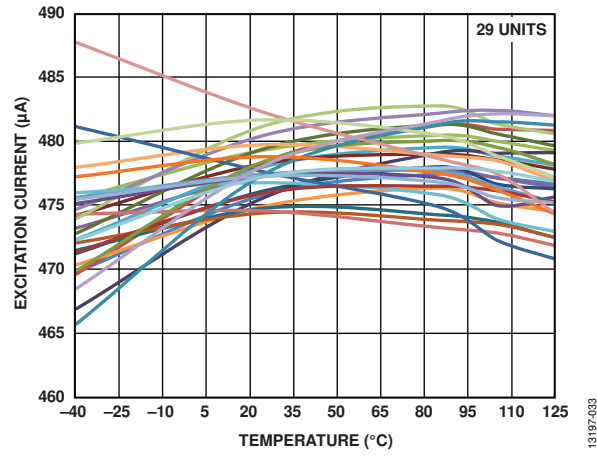


Figure 33. Excitation Current Drift (500 µA)

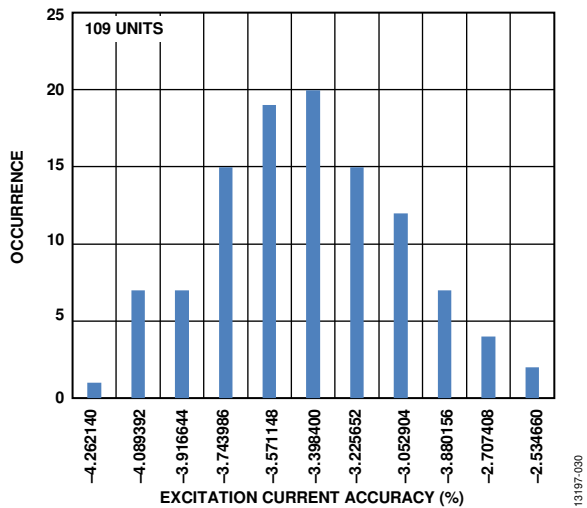


Figure 31. IOUTx Current Initial Accuracy Histogram (500 µA)

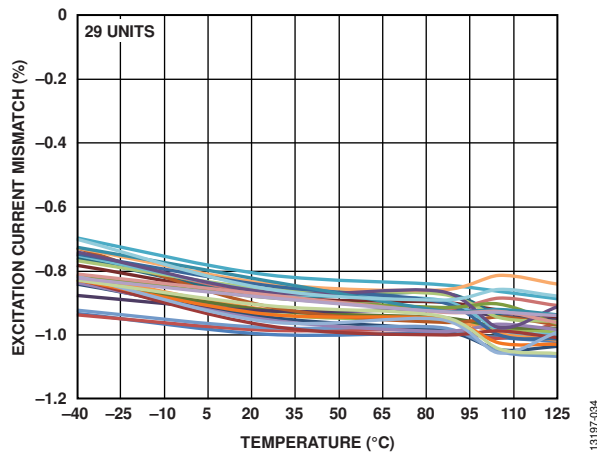


Figure 34. Excitation Current Drift Matching (500 µA)

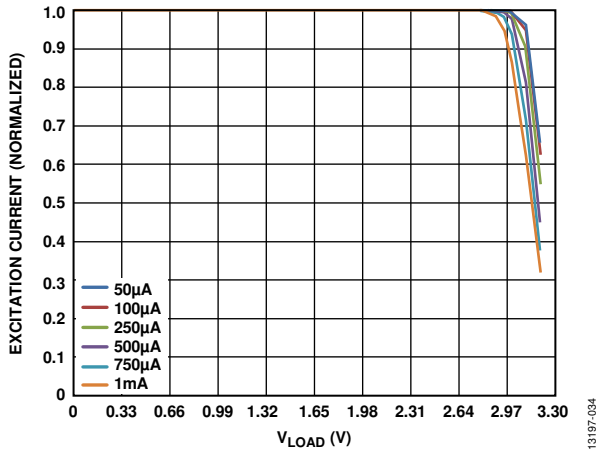


Figure 35. Output Compliance ($A_{V_{DD}} = 3.3\text{ V}$)

13197-034

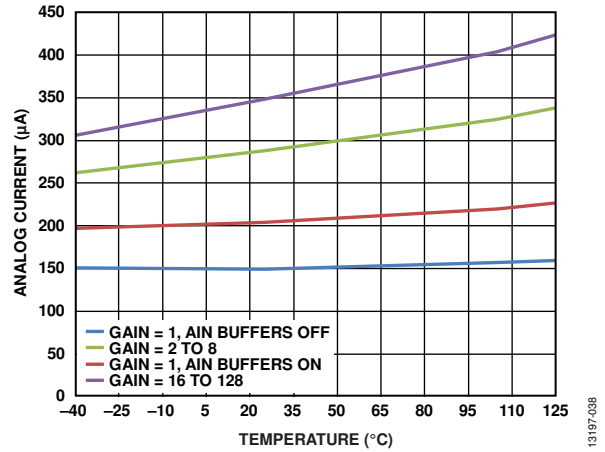


Figure 38. Analog Current vs. Temperature (Mid Power Mode)

13197-038

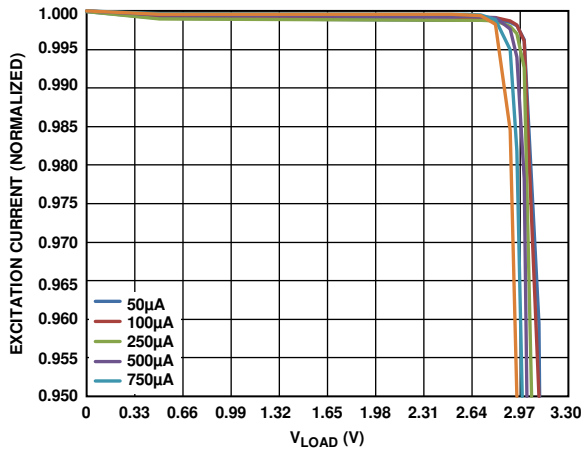


Figure 36. Output Compliance ($A_{V_{DD}} = 3.3\text{ V}$)

13197-035

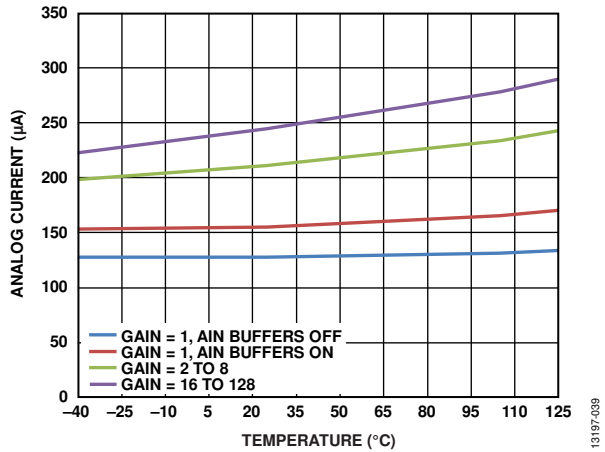


Figure 39. Analog Current vs. Temperature (Low Power Mode)

13197-039

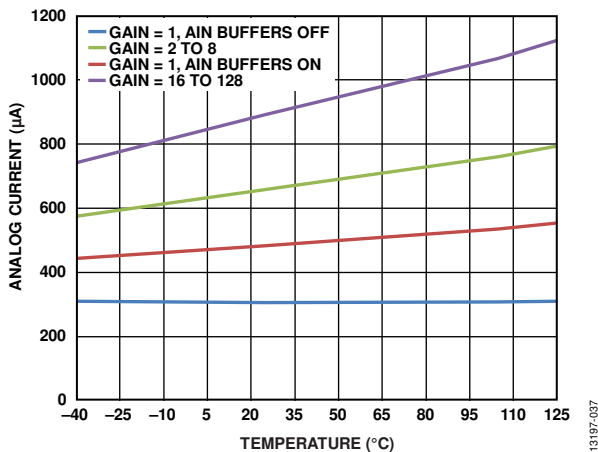


Figure 37. Analog Current vs. Temperature (Full Power Mode)

13197-037

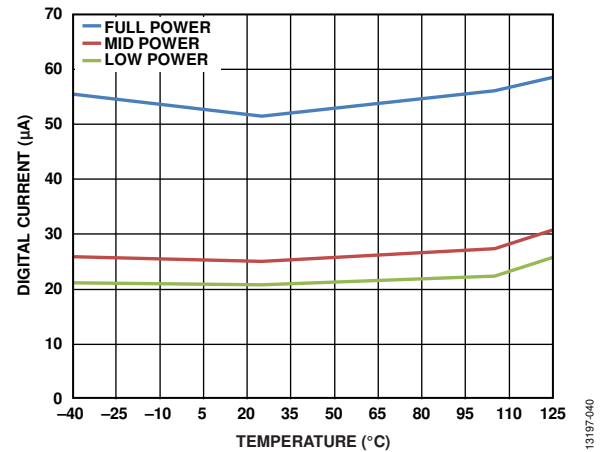


Figure 40. Digital Current vs. Temperature

13197-040

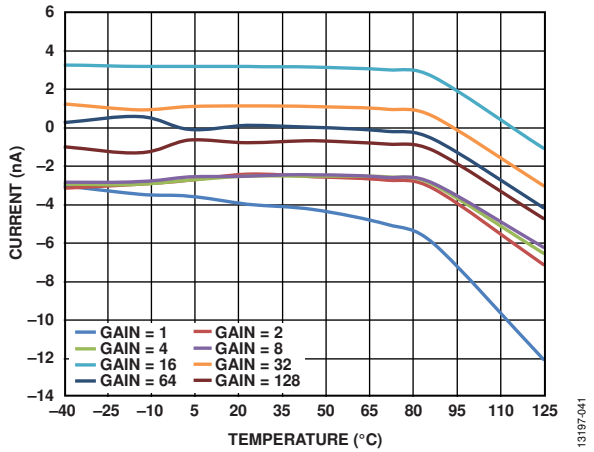


Figure 41. Absolute Analog Input Current vs. Temperature (Full Power Mode)

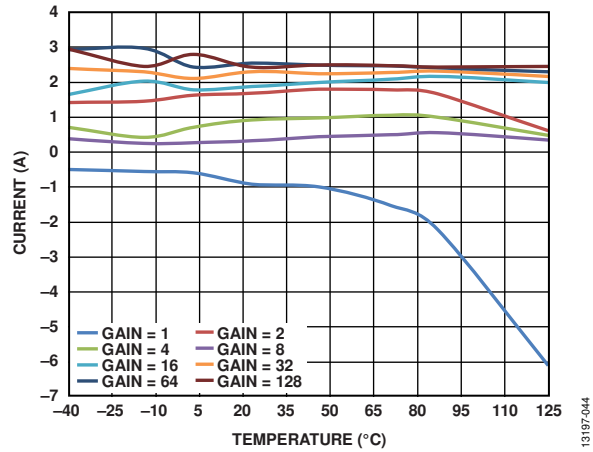


Figure 44. Differential Analog Input Current vs. Temperature (Full Power Mode)

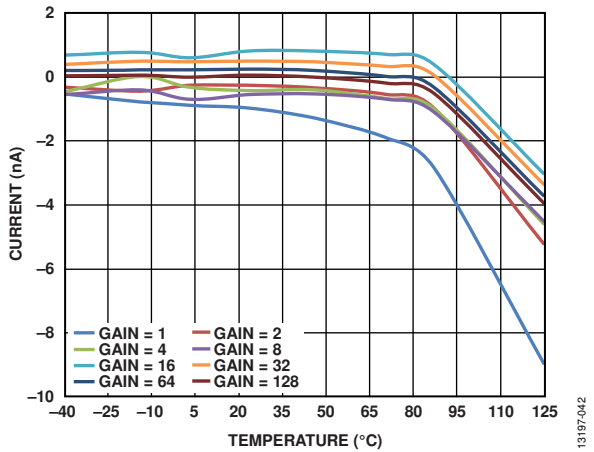


Figure 42. Absolute Analog Input Current vs. Temperature (Mid Power Mode)

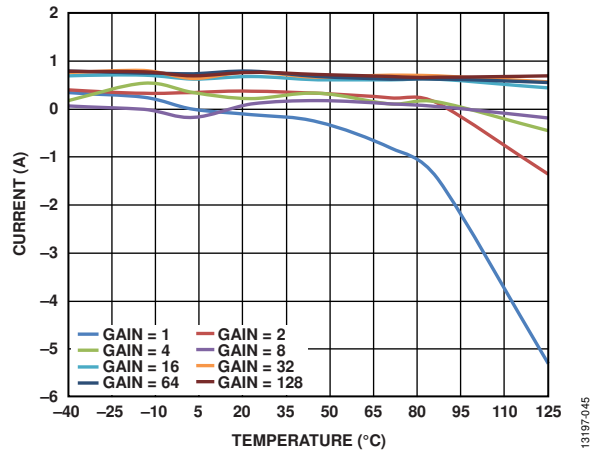


Figure 45. Differential Analog Input Current vs. Temperature (Mid Power Mode)

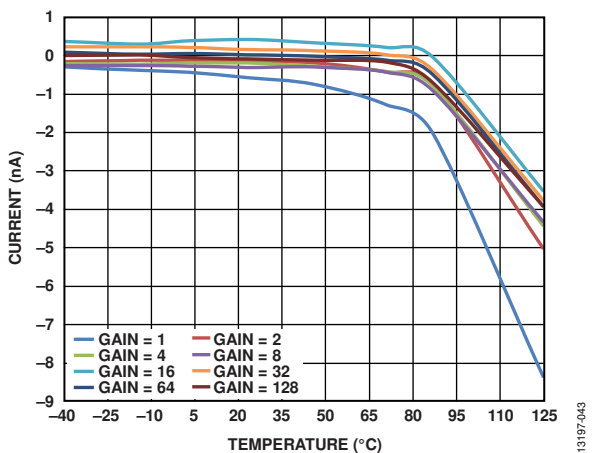


Figure 43. Absolute Analog Input Current vs. Temperature (Low Power Mode)

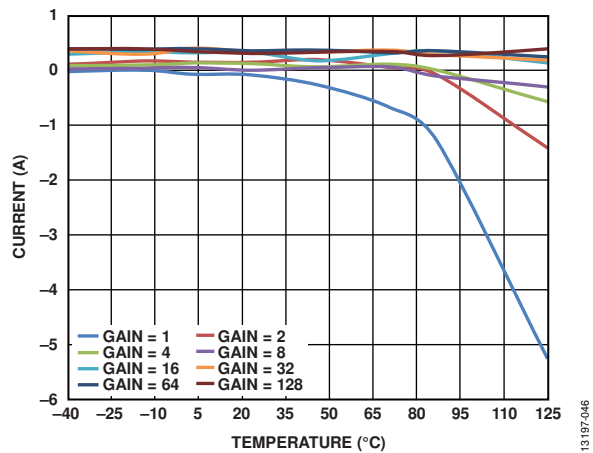


Figure 46. Differential Analog Input Current vs. Temperature (Low Power Mode)

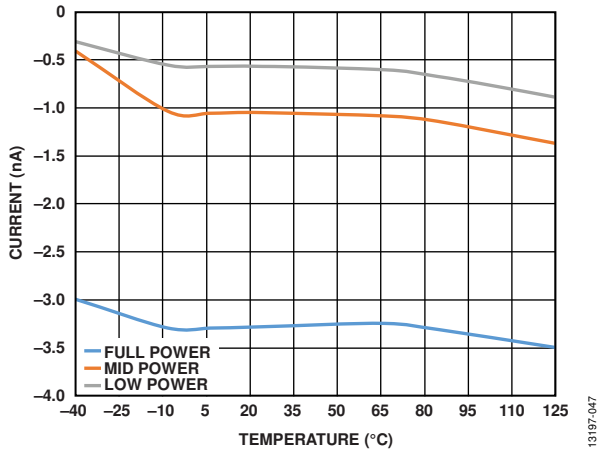


Figure 47. Reference Input Current vs. Temperature (Reference Buffers Enabled)

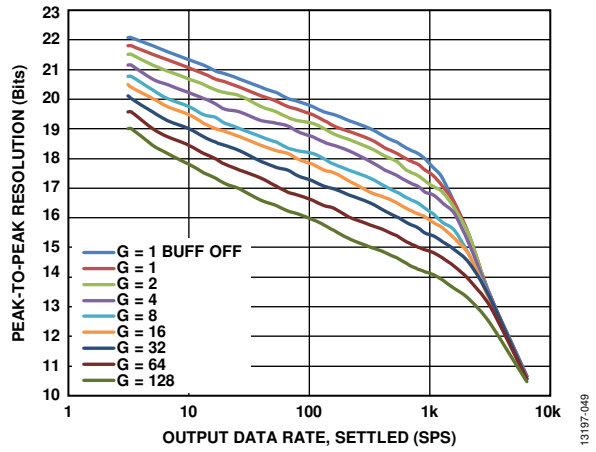


Figure 50. Peak-to-Peak Resolution vs. Output Data Rate (Settled), $Sinc^3$ Filter (Full Power Mode)

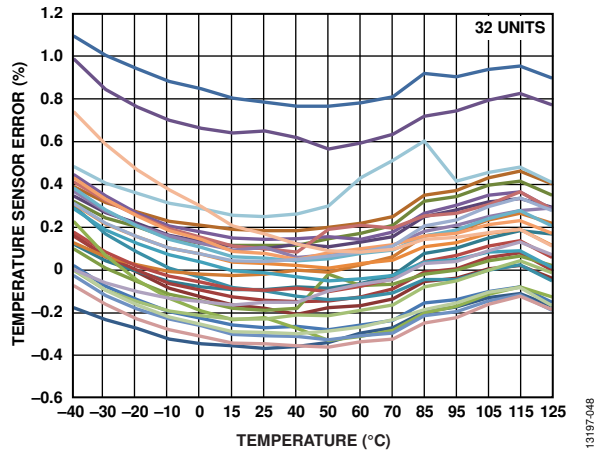


Figure 48. Temperature Sensor Accuracy

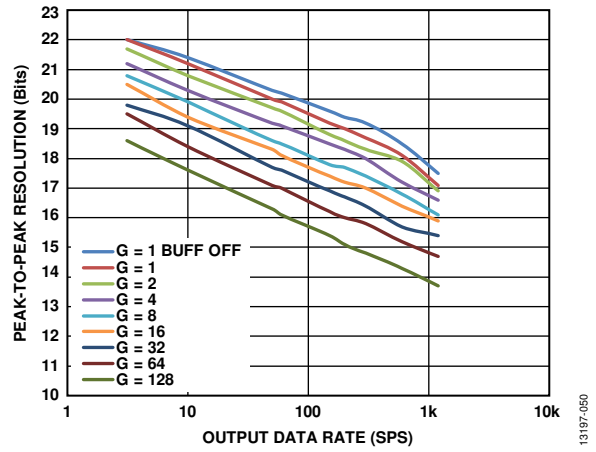


Figure 51. Peak-to-Peak Resolution vs. Output Data Rate, $Sinc^4 + Sinc^1$ Filter (Full Power Mode)

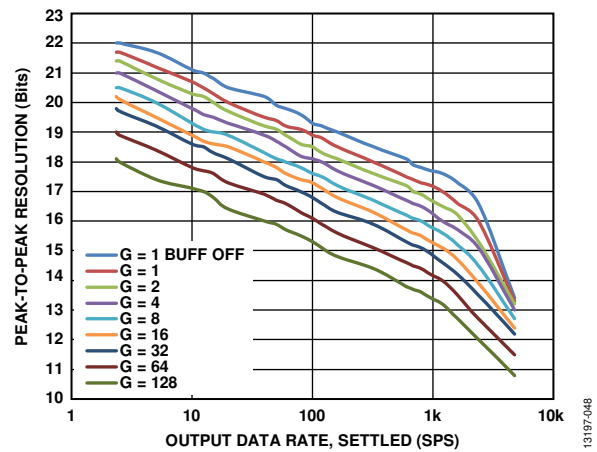


Figure 49. Peak-to-Peak Resolution vs. Output Data Rate (Settled), $Sinc^4$ Filter (Full Power Mode)

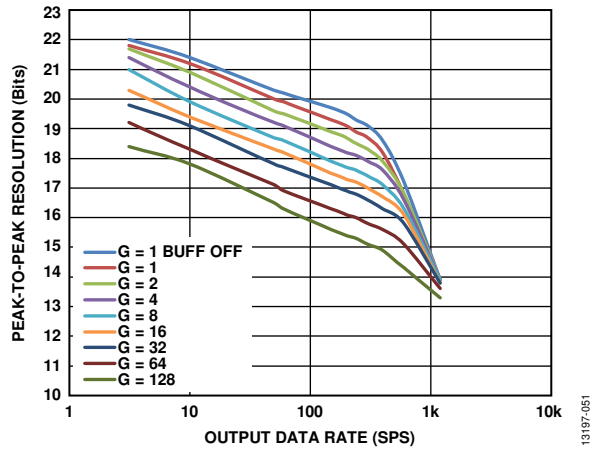


Figure 52. Peak-to-Peak Resolution vs. Output Data Rate, $Sinc^3 + Sinc^1$ Filter (Full Power Mode)

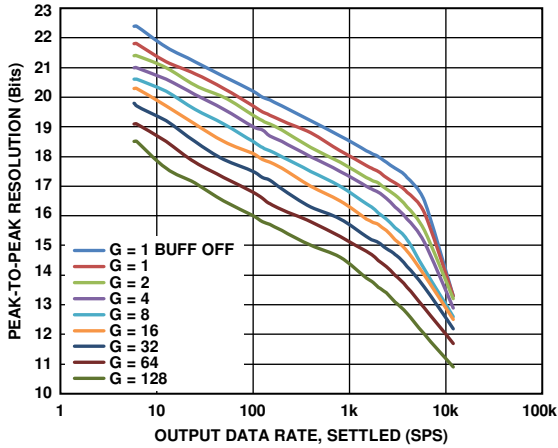


Figure 53. Peak-to-Peak Resolution vs. Output Data Rate (Settled), $Sinc^4$ Filter (Mid Power Mode)

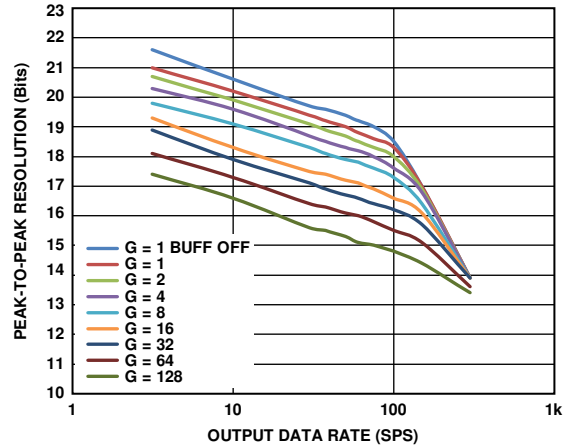


Figure 56. Peak-to-Peak Resolution vs. Output Data Rate, $Sinc^3 + Sinc^1$ Filter (Mid Power Mode)

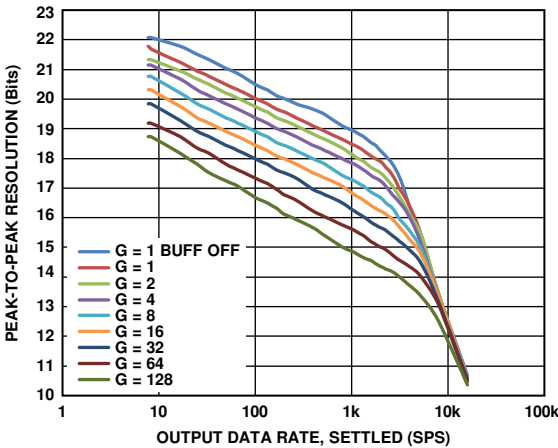


Figure 54. Peak-to-Peak Resolution vs. Output Data Rate (Settled), $Sinc^3$ Filter (Mid Power Mode)

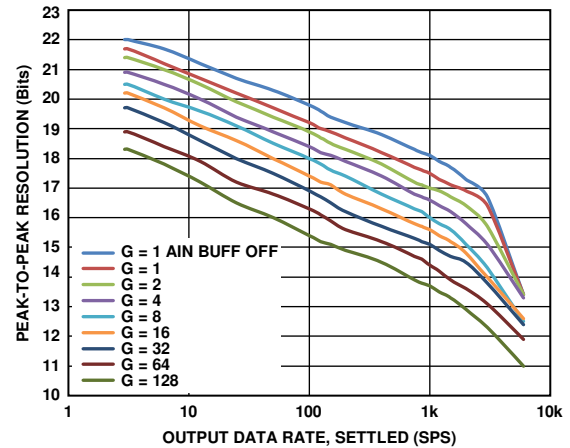


Figure 57. Peak-to-Peak Resolution vs. Output Data Rate (Settled), $Sinc^4$ Filter (Low Power Mode)

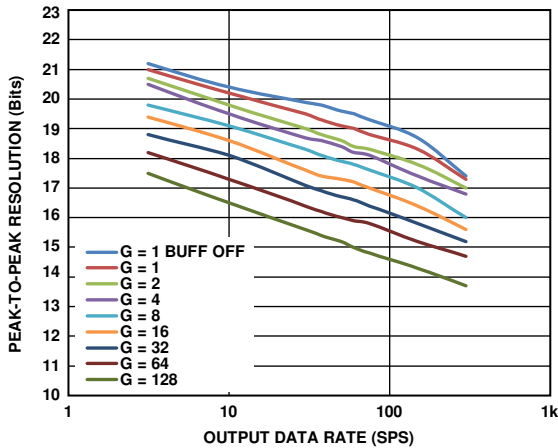


Figure 55. Peak-to-Peak Resolution vs. Output Data Rate, $Sinc^4 + Sinc^1$ Filter (Mid Power Mode)

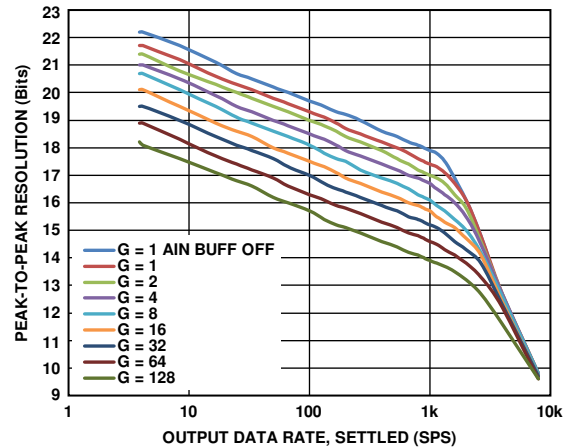


Figure 58. Peak-to-Peak Resolution vs. Output Data Rate (Settled), $Sinc^3$ Filter (Low Power Mode)